



US 20220361343A1

(19) **United States**(12) **Patent Application Publication**
LI et al.(10) **Pub. No.: US 2022/0361343 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **FLEXIBLE CIRCUIT BOARD****Publication Classification**(71) Applicants: **Avary Holding (Shenzhen) Co., Limited.**, Shenzhen (CN); **QING DING PRECISION ELECTRONICS (HUAIAN) CO., LTD.**, Huai an (CN); **GARUDA TECHNOLOGY CO., LTD.**, New Taipei (TW)(51) **Int. Cl.**
H05K 3/46 (2006.01)
H05K 1/11 (2006.01)
H05K 3/28 (2006.01)
(52) **U.S. Cl.**
CPC **H05K 3/4635** (2013.01); **H05K 3/462** (2013.01); **H05K 1/118** (2013.01); **H05K 3/28** (2013.01); **H05K 2203/1377** (2013.01); **H05K 2201/0338** (2013.01)(72) Inventors: **YAO-CAI LI**, Shenzhen (CN); **BIAO LI**, Shenzhen (CN); **HAO-WEN ZHONG**, Shenzhen (CN)(21) Appl. No.: **17/869,934**(57) **ABSTRACT**(22) Filed: **Jul. 21, 2022****Related U.S. Application Data**

(62) Division of application No. 17/114,981, filed on Dec. 8, 2020, now Pat. No. 11,445,618.

(30) **Foreign Application Priority Data**

Nov. 25, 2020 (CN) 202011346515.9

A flexible circuit board includes two first wiring boards, a first adhesive, and a first conductive structure. Each of the two first wiring boards includes a first bent portion, and two first bent portions of the two wiring boards is connected to each other. The first adhesive layer is sandwiched between the two first bent portions. The first conductive structure penetrates the two first bent portions and the first adhesive layer and electrically connects the two first bent portions.

